



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD50N04S3-09		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001795124						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		370.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.791	0.48	0.48	4839	4839
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		582	
	non noble metal	copper	7440-50-8	215.017	58.09	58.17	580825	581581
	non noble metal	aluminium	7429-90-5	2.217	0.60	0.60	5988	5988
wire	non noble metal	aluminium	7429-90-5	2.217	0.60	0.60	5988	5988
encapsulation	organic material	carbon black	1333-86-4	1.259	0.34		3400	
	plastics	epoxy resin	-	22.030	5.95		59509	
	inorganic material	silicondioxide	60676-86-0	102.595	27.71	34.00	277140	340049
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10103	10103
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.039	0.01		106	
	noble metal	silver	7440-22-4	0.049	0.01		133	
	non noble metal	lead	7439-92-1	1.882	0.51	0.53	5083	5322
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.18	5.19	51804	51872
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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